



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2023-06-06
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L552ZET3	E71A*472XXXZ	B	9991	2023-06-06
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20	144	L bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E71A*472XXKZ				6000001.0	1000001.3
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	15.728	mg	supplier	die	Silicon (Si)	7440-21-3		15.118	mg	961216	11497
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	1844	22
				supplier	metallization	Copper (Cu)	7440-50-8		0.258	mg	16404	196
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	64	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.084	mg	5341	64
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	191	2
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	127	2
				supplier	Passivation	Silicon Nitride	12033-89-5		0.066	mg	4196	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.167	mg	10618	127
				Leadframe (C7025 + Ag)	M-011 Other inorganic materials	553.773	mg	Supplier	Leadframe	Copper (Cu)	7440-50-8	
Supplier	Leadframe	Nickel (Ni)	7440-02-0						16.502	mg	29800	12549
Supplier	Leadframe	Silicon (Si)	7440-21-3						3.600	mg	6500	2737
Supplier	Leadframe	Magnesium (Mg)	7439-95-4						0.831	mg	1500	632
Supplier	Leadframe	Silver (Ag)	7440-22-4						2.603	mg	4700	1979
Supplier	Glue or tape	Silver Powder	7440-22-4						3.825	mg	850000	2909
Glue (CRM 1076WA)	M-011 Other inorganic materials	4.500	mg	Supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.239	mg	53000	181
				Supplier	Glue or tape	Epoxy Resin	Trade Secret		0.135	mg	30000	103
				Supplier	Glue or tape	Diluent A	Trade Secret		0.045	mg	10000	34
				Supplier	Glue or tape	Diluent B	Trade Secret		0.135	mg	30000	103
				Supplier	Glue or tape	Hardener	Trade Secret		0.090	mg	20000	68
				Supplier	Glue or tape	Dicyandiamide	461-58-5		0.009	mg	2000	7
				Supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.023	mg	5000	17
				Supplier	Bonding wire	Gold (Au)	7440-57-5		2.475	mg	990000	1882
Bonding wire (Au)	M-011 Other inorganic materials	2.500	mg	Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.025	mg	10000	19
				Supplier	Molding Compound	Epoxy Resin A	Proprietary		14.540	mg	20000	11057
				Supplier	Molding Compound	Epoxy Resin B	Proprietary		14.540	mg	20000	11057
Encapsulation (EME-G6315H)	M-011 Other inorganic materials	727.000	mg	Supplier	Molding Compound	Phenol Resin	Proprietary		39.985	mg	55000	30407
				Supplier	Molding Compound	Carbon Black	1333-86-4		3.999	mg	5500	3041
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		544.887	mg	749500	414362
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		109.050	mg	150000	82928
				Supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999900	8744
Plating (Sn)	M-011 Other inorganic materials	11.500	mg	Supplier	Matte Sn	Impurities	n/a		0.001	mg	100	1